



Zong Zhan Wu 吳宗展

Semiconductor Engineer

Summary

A **semiconductor engineer** with **5+ years of experience** at leading organizations, including **TSMC Fab 12B** and **Camtek**. Proficient in core processes like **Ion Implantation, ALD, and selective wet etching**, alongside metrology tools such as **AFM and 2D/3D AOI calibration**. Managed the rapid deployment (**move-in and hook-up**) of 15 AOI tools, completing **3 buy-offs** within six months. Skilled in **AP8 project sponsorship, client coordination, and hardware troubleshooting** to ensure operational excellence. Furthermore, I **improved particle performance from 20 to 5 and increased tool availability by +5%**. My **comprehensive blend of hands-on technical mastery and strong project execution skills** positions me to drive superior operational results in advanced manufacturing environments.

Contact

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Skill

- Modules Maintenance
- Vacuum Systems
- Electrostatic Chuck
- Gas Panel
- Robot Teaching
- Plasma & RF troubleshooting
- Equipment Hook-up & Buy-offs
- Client Coordination

Education

- Dept. of Biomedical Engineering
National Cheng Kung University
2016.09 – 2019.03
- Dept. of Applied Mathematics
National Chiao Tung University
2012.09 – 2016.06

Certification

- English:
TOEIC 740 (2023.06)
- Automatic control:
丙級工業配線 (2024.09)
- Water supply engineering:
丙級自來水配管(2024.11)

Experience

Customer Service Engineer 2025.03 – 2025.09 *Camtek AOI Equipment*

- Served as AP8 Installation Progress Sponsor, tracking materials, schedules, and coordinating with TSMC customers.
- Completed hook-up & move-in of 15 tools and buy-off of 3 tools within 6 months.
- Mastered 2D/3D measurement calibration in first 3 months and operated independently.
- Troubleshoot robot controller connection issues, ensuring system stability and production accuracy.

Process Integration Engineer 2024.01 – 2025.03 Core Facility Center, National Cheng Kung University

- Specialized in surface modification and selective wet etching processes.
- Excelled in AFM surface roughness analysis and ALD deposition.
- Conducted research on silicon etching inhibitors and failure mode analysis of experimental outcomes.

Ion Implanter Equipment Engineer 2019.09 – 2022.09 TSMC, Fab 12B

- Managed ion implanter equipment for 3 years.
- Skill in high-pressure, ion plasma, vacuum, and pumping systems.
- Improved particle performance from 20 to 5 in germanium implant process, raising tool availability from 80% to 85%.
- Led rapid response and safety protocols during PH₃ gas leakage incidents.